

Work package: Electronics

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Scope

Develops, manufactures and fully characterises the PACIFIC ASIC, the motherboard and back-end electronics, incl. the specification, and testing of the cabling and powering. For the series production, the WP will prepare test benches for qualification and reliability tests.

Current main activities

- Prototypes of the FE boards
- AMC40 firmware development
- Full system simulation
- Production test bench of the FE boards
- Development of the PACIFIC ASIC (PACIFIC3)
- Tests of PACIFIC1/2

Issues

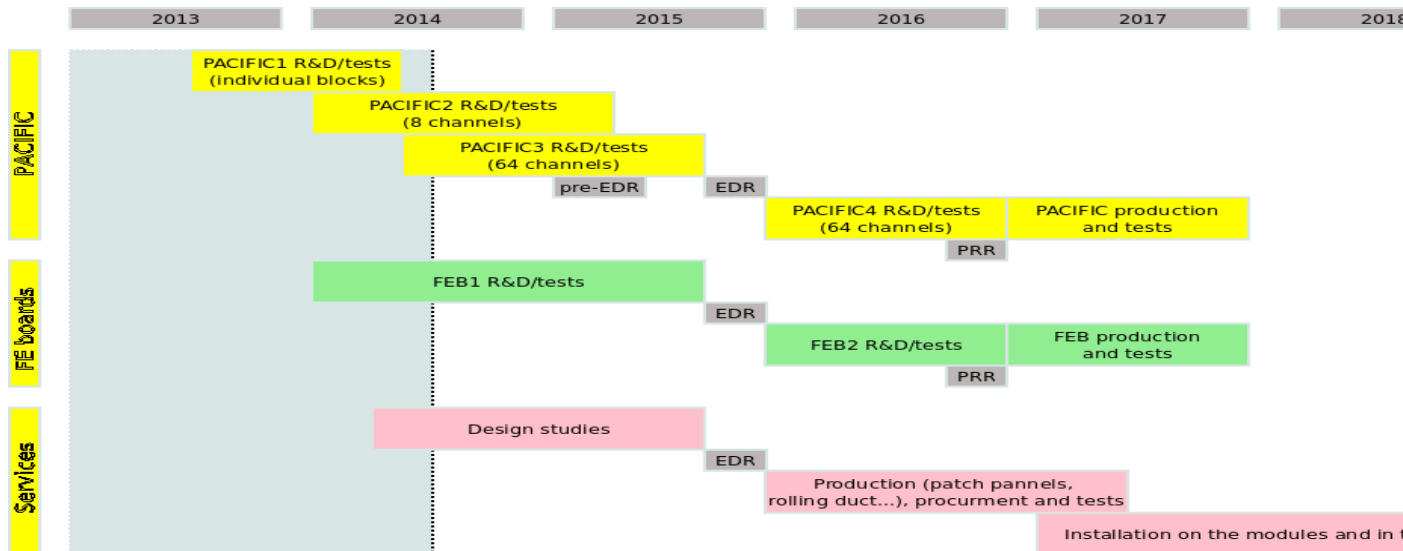
- Spill over (remaining signal in the next event)
- Components quantities
- SiPM characteristics unknown
- Bandwidth needs
- Zero suppression
- Back-end decoding
- Components/optical links quantities
- Power consumption
- Power supplies
- Tight schedule

Contributing institutes

- Barcelona
- CERN
- Clermont-Ferrand
- EPFL
- Heidelberg
- Nikhef
- Valencia

Next milestones and reviews

SciFiElecTronics < LHCb < TWiki



- PACIFIC pre-EDR : Q1 2015
- PACIFIC EDR : EQ3-Q4 2015
- Electronics EDR: EQ3-Q4 2015
- PACIFIC EDR : EQ3-Q4 2016
- Electronics EDR: EQ3-Q4 2016

Further links and material

- SciFiElectronics page

-- ChanalHerve - 26 Jun 2014

- planning.png:

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